

5G Chipset Market by IC Type (ASIC, RFIC, Cellular IC, and mmWave IC), Operational Frequency (Sub 6GHz, Between 26 & 39 GHz, and Above 39 GHz), Product (Devices, Customer Premises Equipment, and Network Infrastructure Equipment), and Industry Vertical (Automotive & Transportation, Energy & Utilities, Healthcare, Retail, Consumer Electronics, Industrial Automation, and Others): Global Opportunity Analysis and Industry Forecast, 2020 - 2026

<https://marketpublishers.com/r/557A70C3B1AEN.html>

Date: December 2018

Pages: 333

Price: US\$ 5,370.00 (Single User License)

ID: 557A70C3B1AEN

Abstracts

5G Chipset Market Overview:

The global 5G Chipset market is expected to be \$2,120.0 million in 2020 and is projected to reach \$22,929.0 million by 2026, registering a CAGR of 48.7% from 2020 to 2026.

5G chipset is the principal component in consumer devices, customer premise equipment, and network infrastructure equipment, which allows the end-user to form the wireless network based on 5G standard. Proliferation of devices using the internet has constituted the demand for an entirely new wireless infrastructure called 5G. Fifth generation wireless (5G) is described as the next generation of mobile networks beyond the current 4G LTE mobile network. These networks are expected to expand broadband wireless services beyond mobile internet to Internet of Things (IoT) and critical communication segments to enable a perceived fully ubiquitous connected world. 5G is

expected to deliver new levels of efficiency and performance empowering new user experiences and connection of new industries. It is a kind of network or a platform for innovations that is expected to not only improve mobile broadband services but also facilitate the expansion of mobile networks to support a vast variety of devices and services. It would also facilitate the interconnection of new industries enabling enhanced efficiency and minimizing cost. With the establishment of 5G infrastructure, 5G chipset opens different opportunities and redefines broad range of industries with connected services from transportation to entertainment, education to retail, and from healthcare to consumer electronics.

The companies operating in the market have adopted strategies such as collaboration, partnership, product launch, R&D, and acquisition, to increase their market share and expand their geographical presence. The global 5G chipset market is analyzed and estimated in accordance with the impact of the drivers, restraints, and opportunities. The period studied in this report is 2020-2026, wherein the forecast period is 2020-2026.

The report includes the study of the global 5G chipset market with respect to the growth prospects and restraints based on the regional analysis. The study includes Porter's five forces analysis of the industry to determine the impact of suppliers, competitors, new entrants, substitutes, and buyers on the market growth.

The market is segmented based on IC type, operational frequency, product, and industry vertical. IC type segment covered in this study includes radio frequency integrated circuit (RFIC), application-specific integrated circuit (ASIC), cellular integrated circuit (Cellular IC), and millimeter wave integrated circuit (mmWave IC). Based on operational frequency, the market is divided into sub-6 GHz, between 26 & 39 GHz, and above 39 GHz. Based on product, the market is classified into devices, customer premises equipment (CPE), and network infrastructure equipment. By industry vertical, it is categorized into automotive & transportation, energy & utilities, healthcare, retail, consumer electronics, industrial automation, and others. By region, the market is analyzed across North America, Europe, Asia-Pacific, and LAMEA.

The key players profiled in the report include Qualcomm Technologies, Inc., Broadcom, Intel Corporation, Nokia Corporation, Samsung Electronics Co., Ltd., Mediatek Inc., Xilinx Inc., Huawei Technologies Co., Ltd., Qorvo, and Infineon Technologies AG.

Key Benefits for 5G Chipset Market:

This study comprises an analytical depiction of the global 5G chipset market with the current trends and future estimations to depict the imminent investment pockets.

The overall market potential is determined to understand the profitable trends to gain a strong foothold in the market.

The report presents information related to key drivers, restraints, and opportunities with a detailed impact analysis.

The current market is quantitatively analyzed from 2020 to 2026 to highlight the financial competency of the market.

Porter's five forces analysis illustrates the potency of the buyers and suppliers.

5G Chipset Key Market Segments:

By IC Type

ASIC

RFIC

Cellular IC

mmWave IC

By Operational Frequency

Sub 6GHz

Between 26 & 39 Ghz

Above 39 Ghz

By Product

Devices

Customer Premises Equipment

Network Infrastructure Equipment

By Industry Vertical

Automotive & Transportation

Energy & Utilities

Healthcare

Retail

Consumer Electronics

Industrial Automation

Others

By Region

North America

U.S.

Canada

Mexico

Europe

UK

Germany

France

Russia

Rest of Europe

Asia-Pacific

China

Japan

India

South Korea

Rest of Asia-Pacific

LAMEA

Latin America

Middle East

Africa

Key Market Players Profiled

Qualcomm Technologies, Inc.

Broadcom

Intel Corporation

Nokia Corporation

Samsung Electronics Co., Ltd.

Mediatek Inc.

Xilinx Inc.

Huawei Technologies Co., Ltd.

Qorvo

Infineon Technologies AG

Contents

CHAPTER 1: INTRODUCTION

- 1.1. REPORT DESCRIPTION
- 1.2. KEY BENEFITS FOR STAKEHOLDERS
- 1.3. KEY MARKET SEGMENTS
- 1.4. RESEARCH METHODOLOGY
 - 1.4.1. Primary research
 - 1.4.2. Secondary research
 - 1.4.3. Analyst tools and models

CHAPTER 2: EXECUTIVE SUMMARY

- 2.1. CXO PERSPECTIVE

CHAPTER 3: MARKET OVERVIEW

- 3.1. MARKET DEFINITION AND SCOPE
- 3.2. KEY FINDINGS
 - 3.2.1. Top impacting factors
 - 3.2.2. Top investment pockets
 - 3.2.3. Top winning strategies
- 3.3. PORTERS FIVE FORCES ANALYSIS
- 3.4. MARKET SHARE ANALYSIS (2020)
- 3.5. MARKET DYNAMICS
 - 3.5.1. Drivers
 - 3.5.1.1. Proliferation of M2M/IoT connections
 - 3.5.1.2. Increase in demand for mobile broadband services
 - 3.5.2. Restraint
 - 3.5.2.1. High investment and Technological & Infrastructure challenges in the implementation of 5G network
 - 3.5.2.2. Privacy and Security Concern
 - 3.5.3. Opportunities
 - 3.5.3.1. Rise in government initiatives for building smart cities in Asia-Pacific

CHAPTER 4: 5G CHIPSET MARKET, BY IC TYPE

- 4.1. OVERVIEW

4.2. ASIC

- 4.2.1. Key market trends, growth factors and opportunities
- 4.2.2. Market size and forecast, by region
- 4.2.3. Market analysis by country

4.3. RFIC

- 4.3.1. Key market trends, growth factors, and opportunities
- 4.3.2. Market size and forecast, by region
- 4.3.3. Market analysis by country

4.4. CELLULAR IC

- 4.4.1. Key market trends, growth factors, and opportunities
- 4.4.2. Market size and forecast, by region
- 4.4.3. Market analysis by country

4.5. MMWAVE IC

- 4.5.1. Key market trends, growth factors, and opportunities
- 4.5.2. Market size and forecast, by region
- 4.5.3. Market analysis by country

CHAPTER 5: 5G CHIPSET MARKET, BY OPERATIONAL FREQUENCY

5.1. OVERVIEW

5.2. SUB 6GHZ

- 5.2.1. Key market trends, growth factors and opportunities
- 5.2.2. Market size and forecast, by region
- 5.2.3. Market analysis by country

5.3. BETWEEN 26 & 39 GHZ

- 5.3.1. Key market trends, growth factors, and opportunities
- 5.3.2. Market size and forecast, by region
- 5.3.3. Market analysis by country

5.4. ABOVE 39 GHZ

- 5.4.1. Key market trends, growth factors, and opportunities
- 5.4.2. Market size and forecast, by region
- 5.4.3. Market analysis by country

CHAPTER 6: 5G CHIPSET MARKET, BY PRODUCT

6.1. OVERVIEW

6.2. DEVICES

- 6.2.1. Key market trends, growth factors and opportunities
- 6.2.2. Market size and forecast, by region

6.2.3. Market analysis by country

6.3. CUSTOMER PREMISES EQUIPMENT

6.3.1. Key market trends, growth factors, and opportunities

6.3.2. Market size and forecast, by region

6.3.3. Market analysis by country

6.4. NETWORK INFRASTRUCTURE EQUIPMENT

6.4.1. Key market trends, growth factors, and opportunities

6.4.2. Market size and forecast, by region

6.4.3. Market analysis by country

CHAPTER 7: 5G CHIPSET MARKET, BY INDUSTRY VERTICAL

7.1. OVERVIEW

7.2. AUTOMOTIVE & TRANSPORTATION

7.2.1. Key market trends, growth factors and opportunities

7.2.2. Market size and forecast, by region

7.2.3. Market analysis by country

7.3. ENERGY & UTILITIES

7.3.1. Key market trends, growth factors and opportunities

7.3.2. Market size and forecast, by region

7.3.3. Market analysis by country

7.4. HEALTHCARE

7.4.1. Key market trends, growth factors and opportunities

7.4.2. Market size and forecast, by region

7.4.3. Market analysis by country

7.5. RETAIL

7.5.1. Key market trends, growth factors and opportunities

7.5.2. Market size and forecast, by region

7.5.3. Market analysis by country

7.6. CONSUMER ELECTRONICS

7.6.1. Key market trends, growth factors and opportunities

7.6.2. Market size and forecast, by region

7.6.3. Market analysis by country

7.7. INDUSTRIAL AUTOMATION

7.7.1. Key market trends, growth factors and opportunities

7.7.2. Market size and forecast, by region

7.7.3. Market analysis by country

7.8. OTHERS

7.8.1. Key market trends, growth factors and opportunities

7.8.2. Market size and forecast, by region

7.8.3. Market analysis by country

CHAPTER 8: 5G CHIPSET MARKET, BY REGION

8.1. OVERVIEW

8.2. NORTH AMERICA

8.2.1. Key market trends, growth factors, and opportunities

8.2.2. Market size and forecast, by IC Type

8.2.3. Market size and forecast, by Operational Frequency

8.2.4. Market size and forecast, by product

8.2.5. Market size and forecast, by industry vertical

8.2.6. Market analysis by country

8.2.6.1. U.S.

8.2.6.1.1. Market size and forecast, by IC Type

8.2.6.1.2. Market size and forecast, by Operational Frequency

8.2.6.1.3. Market size and forecast, by product

8.2.6.1.4. Market size and forecast, by industry vertical

8.2.6.2. Canada

8.2.6.2.1. Market size and forecast, by IC Type

8.2.6.2.2. Market size and forecast, by Operational Frequency

8.2.6.2.3. Market size and forecast, by product

8.2.6.2.4. Market size and forecast, by industry vertical

8.2.6.3. Mexico

8.2.6.3.1. Market size and forecast, by IC Type

8.2.6.3.2. Market size and forecast, by Operational Frequency

8.2.6.3.3. Market size and forecast, by product

8.2.6.3.4. Market size and forecast, by industry vertical

8.3. EUROPE

8.3.1. Key market trends, growth factors, and opportunities

8.3.2. Market size and forecast, by IC Type

8.3.3. Market size and forecast, by Operational Frequency

8.3.4. Market size and forecast, by product

8.3.5. Market size and forecast, by industry vertical

8.3.6. Market analysis by country

8.3.6.1. U.K.

8.3.6.1.1. Market size and forecast, by IC Type

8.3.6.1.2. Market size and forecast, by Operational Frequency

8.3.6.1.3. Market size and forecast, by product

- 8.3.6.1.4. Market size and forecast, by industry vertical
- 8.3.6.2. Germany
 - 8.3.6.2.1. Market size and forecast, by IC Type
 - 8.3.6.2.2. Market size and forecast, by Operational Frequency
 - 8.3.6.2.3. Market size and forecast, by product
 - 8.3.6.2.4. Market size and forecast, by industry vertical
- 8.3.6.3. France
 - 8.3.6.3.1. Market size and forecast, by IC Type
 - 8.3.6.3.2. Market size and forecast, by Operational Frequency
 - 8.3.6.3.3. Market size and forecast, by product
 - 8.3.6.3.4. Market size and forecast, by industry vertical
- 8.3.6.4. Russia
 - 8.3.6.4.1. Market size and forecast, by IC Type
 - 8.3.6.4.2. Market size and forecast, by Operational Frequency
 - 8.3.6.4.3. Market size and forecast, by product
 - 8.3.6.4.4. Market size and forecast, by industry vertical
- 8.3.6.5. Rest of Europe
 - 8.3.6.5.1. Market size and forecast, by IC Type
 - 8.3.6.5.2. Market size and forecast, by Operational Frequency
 - 8.3.6.5.3. Market size and forecast, by product
 - 8.3.6.5.4. Market size and forecast, by industry vertical
- 8.4. ASIA-PACIFIC
 - 8.4.1. Key market trends, growth factors, and opportunities
 - 8.4.2. Market size and forecast, by IC Type
 - 8.4.3. Market size and forecast, by Operational Frequency
 - 8.4.4. Market size and forecast, by product
 - 8.4.5. Market size and forecast, by industry vertical
 - 8.4.6. Market analysis by country
 - 8.4.6.1. China
 - 8.4.6.1.1. Market size and forecast, by IC Type
 - 8.4.6.1.2. Market size and forecast, by Operational Frequency
 - 8.4.6.1.3. Market size and forecast, by product
 - 8.4.6.1.4. Market size and forecast, by industry vertical
 - 8.4.6.2. Japan
 - 8.4.6.2.1. Market size and forecast, by IC Type
 - 8.4.6.2.2. Market size and forecast, by Operational Frequency
 - 8.4.6.2.3. Market size and forecast, by product
 - 8.4.6.2.4. Market size and forecast, by industry vertical
 - 8.4.6.3. India

- 8.4.6.3.1. Market size and forecast, by IC Type
- 8.4.6.3.2. Market size and forecast, by Operational Frequency
- 8.4.6.3.3. Market size and forecast, by product
- 8.4.6.3.4. Market size and forecast, by industry vertical
- 8.4.6.4. South Korea
 - 8.4.6.4.1. Market size and forecast, by IC Type
 - 8.4.6.4.2. Market size and forecast, by Operational Frequency
 - 8.4.6.4.3. Market size and forecast, by product
 - 8.4.6.4.4. Market size and forecast, by industry vertical
- 8.4.6.5. Rest of Asia-Pacific
 - 8.4.6.5.1. Market size and forecast, by IC Type
 - 8.4.6.5.2. Market size and forecast, by Operational Frequency
 - 8.4.6.5.3. Market size and forecast, by product
 - 8.4.6.5.4. Market size and forecast, by industry vertical
- 8.5. LAMEA
 - 8.5.1. Key market trends, growth factors, and opportunities
 - 8.5.2. Market size and forecast, by IC Type
 - 8.5.3. Market size and forecast, by Operational Frequency
 - 8.5.4. Market size and forecast, by product
 - 8.5.5. Market size and forecast, by industry vertical
 - 8.5.6. Market analysis by country
 - 8.5.6.1. Latin America
 - 8.5.6.1.1. Market size and forecast, by IC Type
 - 8.5.6.1.2. Market size and forecast, by Operational Frequency
 - 8.5.6.1.3. Market size and forecast, by product
 - 8.5.6.1.4. Market size and forecast, by industry vertical
 - 8.5.6.2. Middle East
 - 8.5.6.2.1. Market size and forecast, by IC Type
 - 8.5.6.2.2. Market size and forecast, by Operational Frequency
 - 8.5.6.2.3. Market size and forecast, by product
 - 8.5.6.2.4. Market size and forecast, by industry vertical
 - 8.5.6.3. Africa
 - 8.5.6.3.1. Market size and forecast, by IC Type
 - 8.5.6.3.2. Market size and forecast, by Operational Frequency
 - 8.5.6.3.3. Market size and forecast, by product
 - 8.5.6.3.4. Market size and forecast, by industry vertical

CHAPTER 9: COMPANY PROFILES

9.1. BROADCOM

- 9.1.1. Company overview
- 9.1.2. Company snapshot
- 9.1.3. Operating business segments
- 9.1.4. Product portfolio
- 9.1.5. Business performance
- 9.1.6. Key strategic moves and developments

9.2. HUAWEI TECHNOLOGIES CO., LTD.

- 9.2.1. Company overview
- 9.2.2. Company snapshot
- 9.2.3. Operating business segments
- 9.2.4. Product portfolio
- 9.2.5. Business performance
- 9.2.6. Key strategic moves and developments

9.3. INFINEON TECHNOLOGIES AG

- 9.3.1. Company overview
- 9.3.2. Company snapshot
- 9.3.3. Operating business segments
- 9.3.4. Product portfolio
- 9.3.5. Business performance
- 9.3.6. Key strategic moves and developments

9.4. INTEL CORPORATION

- 9.4.1. Company overview
- 9.4.2. Company snapshot
- 9.4.3. Operating business segments
- 9.4.4. Product portfolio
- 9.4.5. Business performance
- 9.4.6. Key strategic moves and developments

9.5. MEDIATEK INC

- 9.5.1. Company overview
- 9.5.2. Company snapshot
- 9.5.3. Product portfolio
- 9.5.4. Business performance
- 9.5.5. Key strategic moves and developments

9.6. NOKIA CORPORATION

- 9.6.1. Company overview
- 9.6.2. Company snapshot
- 9.6.3. Operating business segments
- 9.6.4. Product portfolio

- 9.6.5. Business performance
- 9.6.6. Key strategic moves and developments
- 9.7. QUALCOMM TECHNOLOGIES, INC.
 - 9.7.1. Company overview
 - 9.7.2. Company snapshot
 - 9.7.3. Operating business segments
 - 9.7.4. Product portfolio
 - 9.7.5. Business performance
 - 9.7.6. Key strategic moves and developments
- 9.8. QORVO
 - 9.8.1. Company overview
 - 9.8.2. Company snapshot
 - 9.8.3. Operating business segments
 - 9.8.4. Product portfolio
 - 9.8.5. Business performance
 - 9.8.6. Key strategic moves and developments
- 9.9. SAMSUNG ELECTRONICS CO. LTD.
 - 9.9.1. Company overview
 - 9.9.2. Company snapshot
 - 9.9.3. Operating business segments
 - 9.9.4. Product portfolio
 - 9.9.5. Business performance
 - 9.9.6. Key strategic moves and developments
- 9.10. XILINX INC.
 - 9.10.1. Company overview
 - 9.10.2. Company snapshot
 - 9.10.3. Operating business segments
 - 9.10.4. Product portfolio
 - 9.10.5. Business performance
 - 9.10.6. Key strategic moves and developments

I would like to order

Product name: 5G Chipset Market by IC Type (ASIC, RFIC, Cellular IC, and mmWave IC), Operational Frequency (Sub 6GHz, Between 26 & 39 GHz, and Above 39 GHz), Product (Devices, Customer Premises Equipment, and Network Infrastructure Equipment), and Industry Vertical (Automotive & Transportation, Energy & Utilities, Healthcare, Retail, Consumer Electronics, Industrial Automation, and Others): Global Opportunity Analysis and Industry Forecast, 2020 - 2026

Product link: <https://marketpublishers.com/r/557A70C3B1AEN.html>

Price: US\$ 5,370.00 (Single User License / Electronic Delivery)

If you want to order Corporate License or Hard Copy, please, contact our Customer Service:

info@marketpublishers.com

Payment

To pay by Credit Card (Visa, MasterCard, American Express, PayPal), please, click button on product page <https://marketpublishers.com/r/557A70C3B1AEN.html>